

ABSTRACT OF THE DISCLOSURE

A method of fabricating a memory device on a laminated circuit board is provided comprising laminating a metal layer to an insulating layer; removing metal from the metal layer to define conductive paths, bonding pads, and rails; and etching the rails to remove metal therefrom. Optionally, etching the rails includes removing all metal from the rails. The rails are defined along at least a portion of the edges of a length of the circuit board where no metal has been removed, and the rails are electrically isolated from the conductive paths and bonding pads.